



# 16×16-Bit CMOS Single Port Multiplier/Accumulator

## ADSP-1110A

### 1.1 Scope.

This specification covers the detail requirements for a monolithic CMOS 16×16-bit multiplier/accumulator integrated circuit.

### 1.2 Part Number.

The complete part number per Table 1 of this specification is as follows:

Device	Part Number
-1	ADSP-1110AS(X)/883B
-2	ADSP-1110AT(X)/883B

### 1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline:

(X)	Package	Description
D	D-28	28-Pin DIP
E	E-28	28-Contact LCC

### 1.3 Absolute Maximum Ratings.

Supply Voltage	.....	-0.3 V to 7 V
Input Voltage	.....	-0.3 V to $V_{DD}$
Output Voltage	.....	-0.3 V to $V_{DD}$
Operating Temperature Range (Ambient)	.....	-55°C to +125°C
Storage Temperature Range	.....	-65°C to +150°C
Lead Temperature (Soldering 10 sec)	.....	+300°C

### 1.5 Thermal Characteristics.

Maximum Thermal Resistance  $\theta_{JC}$ : see MIL-M-38510, Appendix C.

# ADSP-1110A – SPECIFICATIONS

Test	Symbol	Device	Design Limit @ +25°C	Sub Group 1	Sub Group 2, 3	Sub Group 9, 10, 11	Test Condition <sup>1</sup>	Units
Digital Input High Voltage*	V <sub>IH</sub>	-1, 2	2.0	2.2	2.2		V <sub>DD</sub> = max	V min
Digital Input Low Voltage	V <sub>IL</sub>	-1, 2	0.8	0.8	0.8		V <sub>DD</sub> = min	V max
Digital Output High Voltage	V <sub>OH</sub>	-1, 2	2.4	2.4	2.4		V <sub>DD</sub> = min I <sub>OH</sub> = -1 mA	V min
Digital Output Low Voltage*	V <sub>OL</sub>	-1, 2	0.4	0.6	0.6		V <sub>DD</sub> = min I <sub>OH</sub> = +4 mA	V max
Digital Input High Current	I <sub>IH</sub>	-1, 2	10	10	10		V <sub>DD</sub> = max V <sub>IN</sub> = +5.0 V	μA max
Digital Input Low Current	I <sub>IL</sub>	-1, 2	10	10	10		V <sub>DD</sub> = max V <sub>IN</sub> = 0.0 V	μA max
Three-State Leakage* Current Low	I <sub>OZL</sub>	-1, 2	50	50	50		V <sub>DD</sub> = max V <sub>IL</sub> = 0 V (High Z)	μA max
Three-State Leakage Current High	I <sub>OZH</sub>	-1, 2	50	50	50		V <sub>DD</sub> = max V <sub>IH</sub> = max (High Z)	μA max
Supply Current*	I <sub>DD1</sub>	-1, 2	70	80	80		V <sub>DD</sub> = max; TTL Inputs; f = max	mA max
	I <sub>DD2</sub>	-1, 2	35	40	40		V <sub>DD</sub> = max * All V <sub>IN</sub> = 2.4 V	mA max
Clock Pulse Width	t <sub>PW</sub>	-1, 2	15			15	Note 2	ns min
Input Control Hold Time	t <sub>CH</sub>	-1, 2	5			6	Note 2	ns min
Input Data Setup Time	t <sub>DS</sub>	-1, 2	15			15	Note 2	ns min
Clock Period*	t <sub>CLK</sub>	-1	50			60	Note 2	ns min
		-2	42.5			50		
Input Control Setup Time	t <sub>CS</sub>	-1	25			25	Note 2	ns min
		-2	20			20		
Input Data Hold Time*	t <sub>DH</sub>	-1, 2	3			4	Note 2	ns min
Multiply/Accumulate Time*	t <sub>MAC</sub>	-1	100			120	Note 2	ns max
		-2	85			100		
Control to Valid Output*	t <sub>D</sub>	-1	30			30	Note 2	ns max
		-2	25			30		
Control to Valid Output* with Saturation	t <sub>DSAT</sub>	-1	35			40	Note 2	ns max
		-2	32			35		
Output Driver Disable Time	t <sub>DIS</sub>	-1, 2	25			25	Notes 2 and 3	ns max
Control to Overflow Flag*	t <sub>O</sub>	-1	30			35	Note 2	ns max
		-2	25			30		
Control to Overflow Flag* W/SL	t <sub>LO</sub>	-1	40			45	Note 2	ns max
		-2	35			45		

## NOTES

\*Indicates that a limit for this parameter has changed from REV. C.

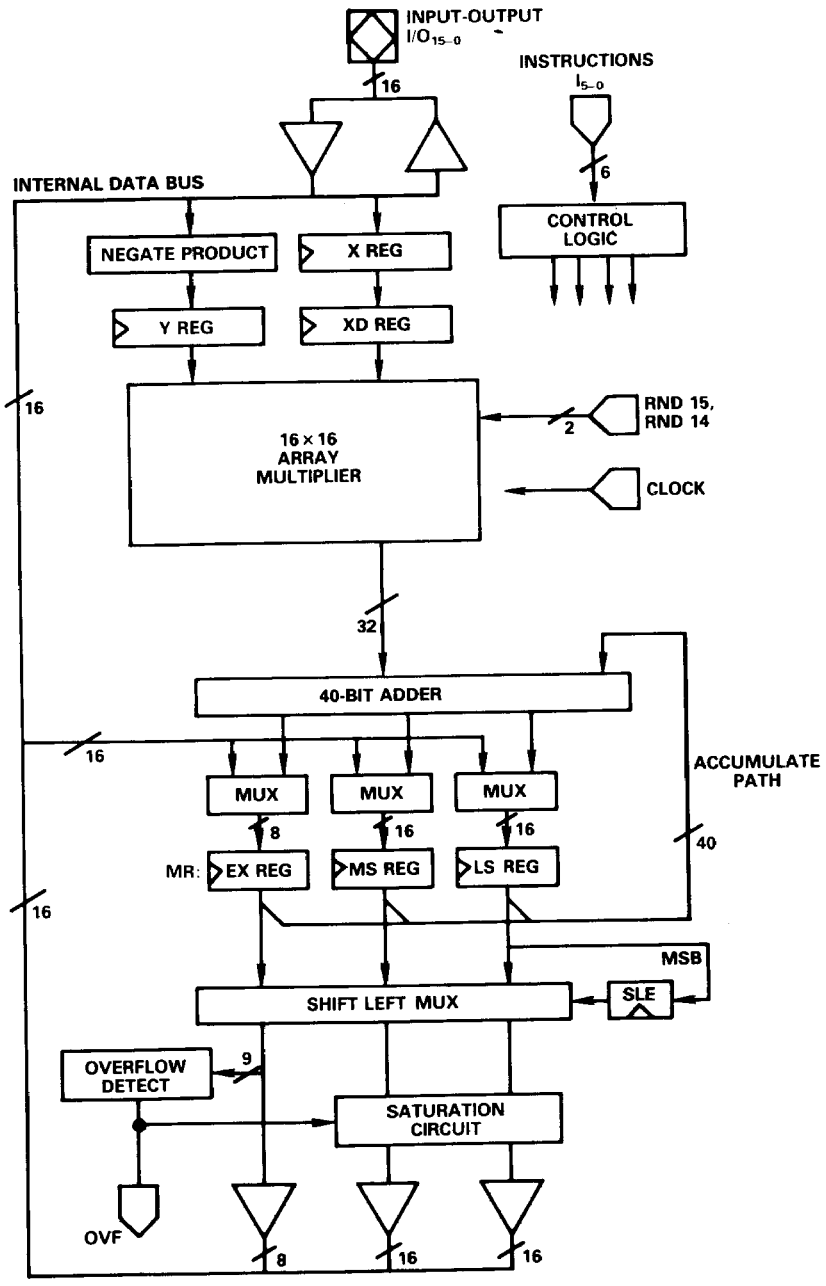
<sup>1</sup>T<sub>A</sub> = +25°C; V<sub>DD</sub> = +4.5 V min to +5.5 V max (unless otherwise noted).

<sup>2</sup>TTL inputs of 0 V and +3.0 V; V<sub>DD</sub> = +4.5 V, rise time = 5 ns, and timing transitions, per Figure 1, measured at +1.5 V (unless otherwise noted).

<sup>3</sup>Transitions measured per Figure 2.

Table 1.

## 3.2.1 Functional Block Diagrams and Terminal Assignments.



Pin Assignments

PIN	FUNCTION	PIN	FUNCTION
1	RND15	15	CLK
2	RND14	16	I <sub>3</sub>
3	I/O <sub>14</sub>	17	I <sub>4</sub>
4	I/O <sub>12</sub>	18	I <sub>5</sub>
5	I/O <sub>10</sub>	19	OVF
6	I/O <sub>8</sub>	20	I/O <sub>1</sub>
7	I/O <sub>6</sub>	21	I/O <sub>3</sub>
8	I/O <sub>4</sub>	22	I/O <sub>5</sub>
9	I/O <sub>2</sub>	23	I/O <sub>7</sub>
10	I/O <sub>0</sub>	24	I/O <sub>9</sub>
11	I <sub>0</sub>	25	I/O <sub>11</sub>
12	I <sub>1</sub>	26	I/O <sub>13</sub>
13	I <sub>2</sub>	27	I/O <sub>15</sub>
14	GND	28	V <sub>DD</sub>

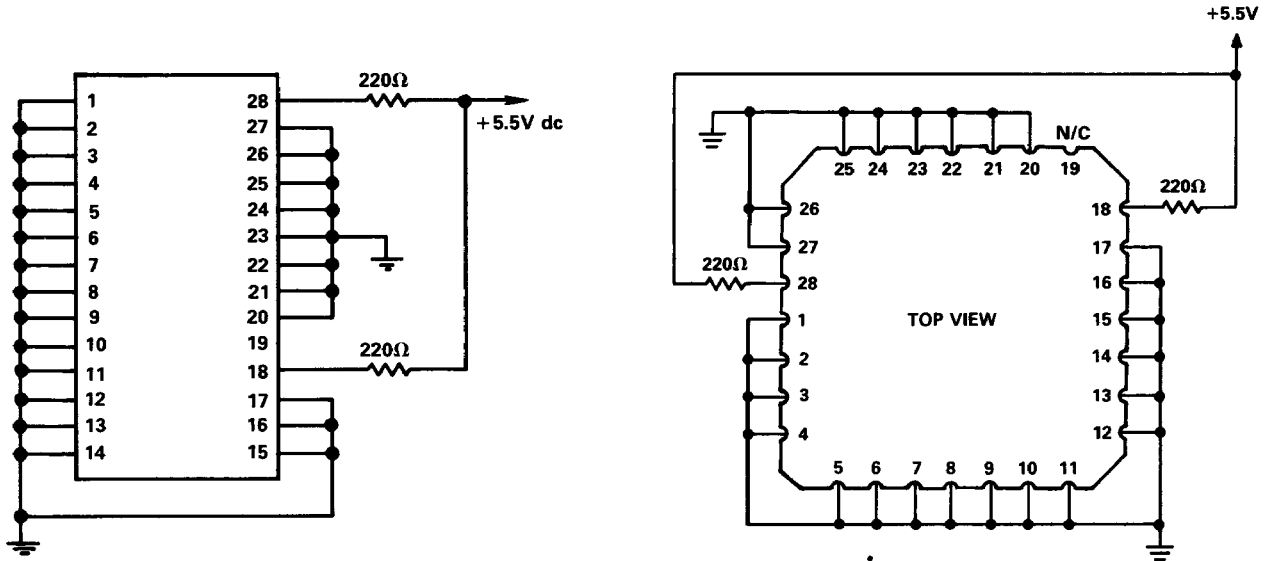
## 3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (105).

# ADSP-1110A

## 4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).



ADSP-1110AD Life Test and Burn-In Circuit

ADSP-1110AE Life Test and Burn-In Circuit

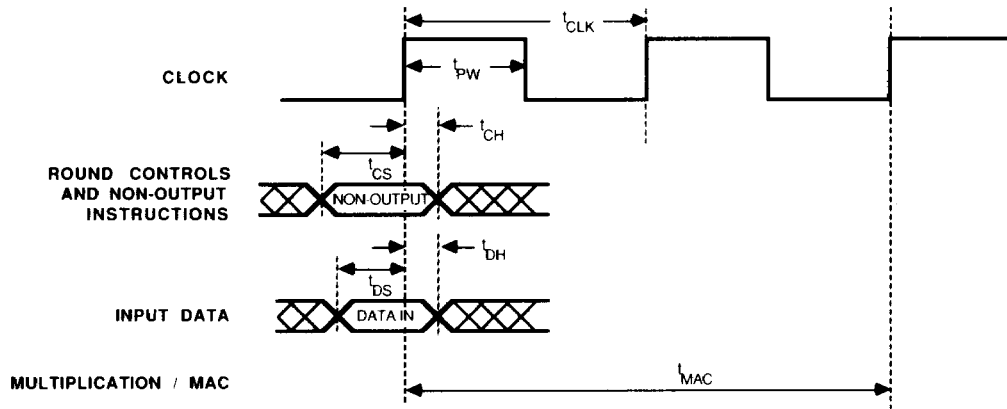


Figure 1. ADSP-1110A Timing: Clock (Synchronous) Operations All Non-Output Instructions

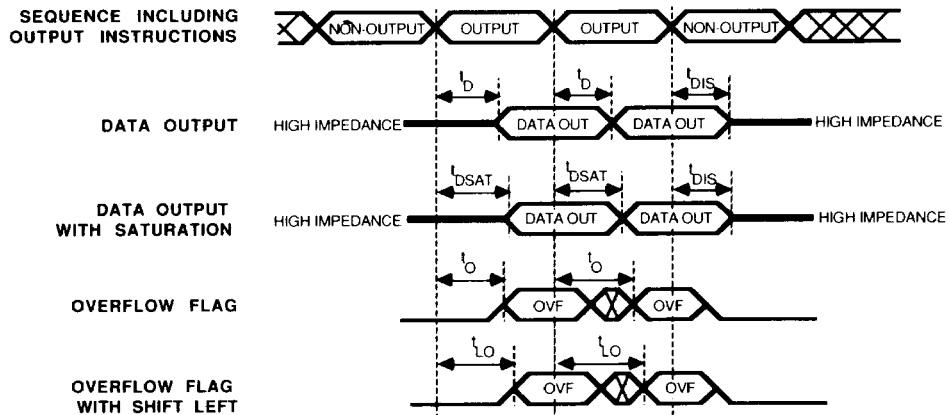


Figure 2. ADSP-1110A Timing: Unlocked (Asynchronous) Operations All Output Instructions

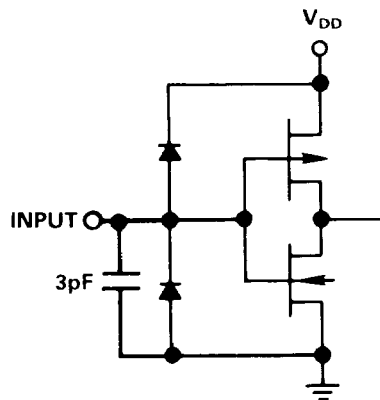


Figure 3. Equivalent Input Circuit

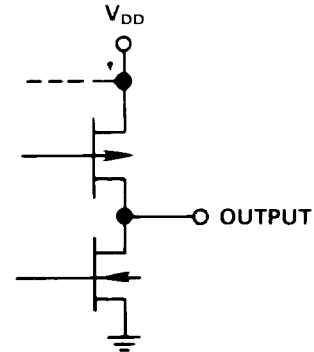


Figure 4. Equivalent Output Circuit

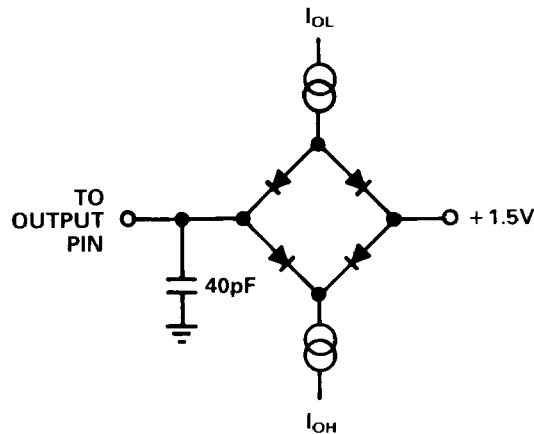


Figure 5. Normal Load Circuit for AC Measurements

# ADSP-1110A

Instruction Group	Instruction	Microcode	Comments
		Instruction 5 4 3 2 1 0	
Miscellaneous	NOP	0 0 0 0 X X	No Operation
	CKMR	0 0 0 1 X X	Clock MR
Input	X = BUS	0 0 1 0 X X	
Preload	LS = BUS	0 1 0 0 0 0	
	MS = BUS	0 1 0 1 X 0	
	EX = BUS	0 1 0 0 1 0	
Transfer	LS = MS	0 1 0 0 0 1	Set SLE register
	MS = EX	0 1 0 1 0 1	
Sign Extend	EX = SIGN EXT MS	0 1 0 0 1 1	
	MS = SIG EXT LS	0 1 0 1 1 1	
Output	BUS = EX	0 0 1 1 0 1	All output instructions are asynchronous I5-I2: 0011 = EX 0110 = MS 0111 = LS I1-I0: 01 = to bus 00 = to bus shifted 10 = to bus shifted w/saturation 11 = to bus w/saturation
	BUS = EX (sl)	0 0 1 1 0 0	
	BUS = MS	0 1 1 0 0 1	
	BUS = MS (sl)	0 1 1 0 0 0	
	BUS = MS (sat)	0 1 1 0 1 1	
	BUS = MS (sl, sat)	0 1 1 0 1 0	
	BUS = LS	0 1 1 1 0 1	
	BUS = LS (sl)	0 1 1 1 0 0	
	BUS = LS (sat)	0 1 1 1 1 1	
	BUS = LS (sl, sat)	0 1 1 1 1 0	
Multi-Operation	Y = BUS; CKMR; $X_{US} * Y_{US}$	1 0 0 X 0 0	Require two cycles to complete. Other instructions can be executed on the second cycle.  I5 = Multiply/MAC operation I4 = Y twos complement I3 = X twos complement I2 = Subtract previous result I1 = Add/subtract previous result from product I0 = Negate product
	Y = BUS; CKMR; $-X_{US} * Y_{US}$	1 0 0 X 0 1	
	Y = BUS; CKMR; $X_{US} * Y_{US} + MR$	1 0 0 0 1 0	
	Y = BUS; CKMR; $-X_{US} * Y_{US} + MR$	1 0 0 0 1 1	
	Y = BUS; CKMR; $X_{US} * Y_{US} - MR$	1 0 0 1 1 0	
	Y = BUS; CKMR; $-X_{US} * Y_{US} - MR$	1 0 0 1 1 1	
	Y = BUS; CKMR; $X_{TC} * Y_{US}$	1 0 1 X 0 0	
	Y = BUS; CKMR; $-X_{TC} * Y_{US}$	1 0 1 X 0 1	
	Y = BUS; CKMR; $X_{TC} * Y_{US} + MR$	1 0 1 0 1 0	
	Y = BUS; CKMR; $-X_{TC} * Y_{US} + MR$	1 0 1 0 1 1	
	Y = BUS; CKMR; $X_{TC} * Y_{US} - MR$	1 0 1 1 1 0	
	Y = BUS; CKMR; $-X_{TC} * Y_{US} - MR$	1 0 1 1 1 1	
	Y = BUS; CKMR; $X_{US} * Y_{TC}$	1 1 0 X 0 0	
	Y = BUS; CKMR; $-X_{US} * Y_{TC}$	1 1 0 X 0 1	
	Y = BUS; CKMR; $X_{US} * Y_{TC} + MR$	1 1 0 0 1 0	
	Y = BUS; CKMR; $-X_{US} * Y_{TC} + MR$	1 1 0 0 1 1	
	Y = BUS; CKMR; $X_{US} * Y_{TC} - MR$	1 1 0 1 1 0	
	Y = BUS; CKMR; $-X_{US} * Y_{TC} - MR$	1 1 0 1 1 1	
	Y = BUS; CKMR; $X_{TC} * Y_{TC}$	1 1 1 X 0 0	
	Y = BUS; CKMR; $-X_{TC} * Y_{TC}$	1 1 1 X 0 1	
	Y = BUS; CKMR; $X_{TC} * Y_{TC} + MR$	1 1 1 0 1 0	
	Y = BUS; CKMR; $-X_{TC} * Y_{TC} + MR$	1 1 1 0 1 1	
	Y = BUS; CKMR; $X_{TC} * Y_{TC} - MR$	1 1 1 1 1 0	
	Y = BUS; CKMR; $-X_{TC} * Y_{TC} - MR$	1 1 1 1 1 1	

## Mnemonic Definitions

=	Assign right side to left.	sl	Shift left.
BUS	16-bit external data bus used for all I/O operations.	sat	Conditional on overflow, saturate the outputted value.
X	Input register for multiplier.	TC	Twos complement number.
Y	Input register for multiplier.	US	Unsigned magnitude number.
EX	8-bit extension register for accumulator.	SIGN	Sign bit (MSB) of specified register.
MS	16-bit most significant product register.	CKMR	Clock product into EX, MS and LS.
LS	16-bit least significant product register.	*	Multiply
MR	40-bit accumulator comprising EX, MS and LS.	X	Microcode instruction bit can be either a 0 or 1.

Table 2. ADSP-1110A Instruction Set